RELIABILITY REPORT

FOR

MAX3266xSA

PLASTIC ENCAPSULATED DEVICES

June 10, 2003

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Written by

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Conclusion

The MAX3266 successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX3266 is a transimpedance preamplifier for 1.25Gbps LAN fiber optic receivers. The circuit features 200nA input-referred noise, 920MHz bandwidth, and 1mA input overload.

The devices operates from a single +3.0V to +5.5V supply and requires no compensation capacitor. It includes a space-saving filter connection that provides positive bias for the photodiode through a 1.5kΩ resistor to V_{CC}. These features allow easy assembly into a TO-46 or TO-56 header with a photodiode.

The 1.25Gbps MAX3266 has a typical optical dynamic range of -24dBm to 0dBm in a shortwave (850nm)configuration or -27dBm to -3dBm in a longwave (1300nm) configuration.

B. Absolute Maximum Ratings

Item	Rating
Supply Voltage (VCC - GND)	-0.5V to +6.0V
IN Current	-4mA to +4mA
FILTER Current	-8mA to +8mA
Voltage at OUT+, OUT-	(VCC - 1.5V) to (VCC + 0.5V)
Storage Temperature Range	-55°C to +150°C
Operating Junction Temperature (die)	-55°C to +150°C
Processing Temperature (die)	+400°C
Lead Temperature (soldering, 10s)	+300°C
Continuous Power Dissipation (Ta = +70°C)	
16-Pin NSO	533mW
Derates above +70°C	
16-Pin NSO	6.7mW/°C

II. Manufacturing Information

A. Description/Function:	1.25Gbps, +3V to +5.5V, Low-Noise Transimpedance Preamplifiers for LANs
B. Process:	GST33
C. Number of Device Transistors:	320
D. Fabrication Location:	Oregon, USA
E. Assembly Location:	Philippines, Thailand or Malaysia
F. Date of Initial Production:	August, 1999

III. Packaging Information

A. Package Type:	**8-NSO**
B. Lead Frame:	Copper
C. Lead Finish:	Solder Plate
D. Die Attach:	Silver-filled Epoxy
E. Bondwire:	Gold (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	# 05-7001-0336
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard JESD22-A112:	Level 1

IV. Die Information

A. Dimensions:	31 x 51 mils
B. Passivation:	Si_3N_4 (Silicon nitride)
C. Interconnect:	Poly / Au
D. Backside Metallization:	None
E. Minimum Metal Width:	Metal1: 1.2; Metal2: 1.2; Metal3: 2.8; Metal4: 5.6 microns (as drawn)
F. Minimum Metal Spacing:	Metal1: 1.3; Metal2: 1.4; Metal3: 2.6; Metal4: 2.6 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:

Jim Pedicord	(Reliability Lab Manager)
Bryan Preeshl	(Executive Director of QA)
Kenneth Huening	(Vice President)

B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.

C. Observed Outgoing Defect Rate: < 50 ppm

D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 150°C biased (static) life test are shown in **Table 1**. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 9823 \times 60 \times 2}$$ (Chi square value for MTTF upper limit)

Thermal acceleration factor assuming a 0.8eV activation energy

$\lambda = 8.09 \times 10^{-9}$ $\lambda = 8.09$ F.I.T. (60% confidence level @ 25°C)

This low failure rate represents data collected from Maxim's reliability qualification and monitor programs. Maxim also performs weekly Burn-In on samples from production to assure the reliability of its processes. The reliability required for lots which receive a burn-in qualification is 59 F.I.T. at a 60% confidence level, which equates to 3 failures in an 80 piece sample. Maxim performs failure analysis on lots exceeding this level. Maxim also performs 1000 hour life test monitors quarterly for each process. This data is published in the Product Reliability Report (**RR-B3A**).

B. Moisture Resistance Tests

Maxim evaluates pressure pot stress from every assembly process during qualification of each new design. Pressure Pot testing must pass a 20% LTPD for acceptance. Additionally, industry standard 85°C/85%RH or HAST tests are performed quarterly per device/package family.

C. E.S.D. and Latch-Up Testing

The HF45-1 die type has been found to have all pins able to withstand a transient pulse of ±1500V, per Mil-Std-883 Method 3015 (r5eference attached ESD Test Circuit). Latch-Up testing has shown that this device withstands a current of ±240mA.

Table 1
Reliability Evaluation Test Results

MAX3266xSA

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 150°C Biased Time = 192 hrs.	DC Parameters & functionality	60	0
Moisture Testing (Note 2)				
Pressure Pot	Ta = 121°C P = 15 psi. RH= 100% Time = 168hrs.	DC Parameters & functionality	77	0
85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters	77	0

Note 1: Life Test Data may represent plastic D.I.P. qualification lots.
Note 2: Generic Package/Process Data

Attachment #1

TABLE II. Pin combination to be tested. 1/ 2/

	Terminal A (Each pin individually connected to terminal A with the other floating)	Terminal B (The common combination of all like-named pins connected to terminal B)
1.	All pins except V_{PS1} 3/	All V_{PS1} pins
2.	All input and output pins	All other input-output pins

1/ Table II is restated in narrative form in 3.4 below.
2/ No connects are not to be tested.
3/ Repeat pin combination I for each named Power supply and for ground

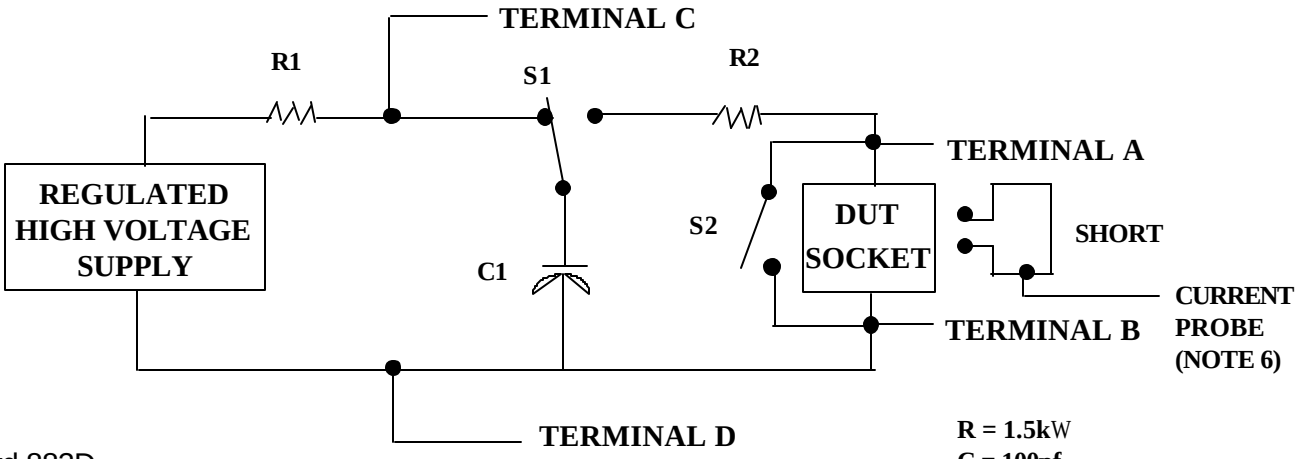
(e.g., where V_{PS1} is V_{DD}, V_{CC}, V_{SS}, V_{BB}, GND, $+V_S$, $-V_S$, V_{REF}, etc).

3.4 Pin combinations to be tested.

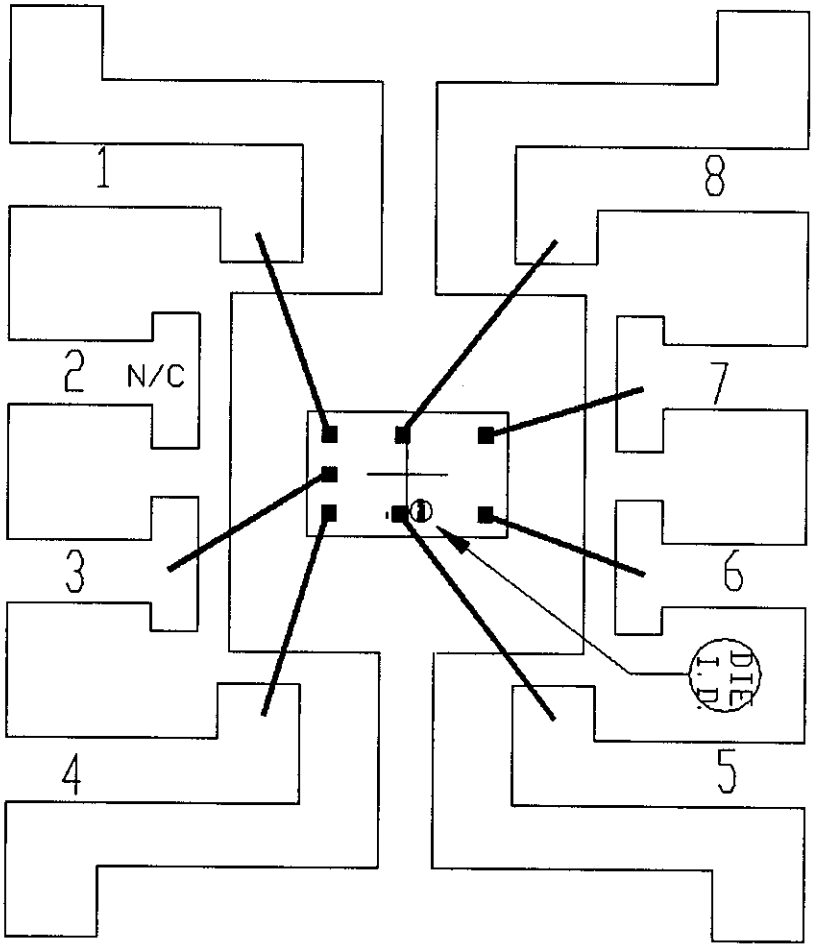
a. Each pin individually connected to terminal A with respect to the device ground pin(s) connected to terminal B. All pins except the one being tested and the ground pin(s) shall be open.

b. Each pin individually connected to terminal A with respect to each different set of a combination of all named power supply pins (e.g., V_{SS1}, or V_{SS2} or V_{SS3} or V_{CC1}, or V_{CC2}) connected to terminal B. All pins except the one being tested and the power supply pin or set of pins shall be open.

c. Each input and each output individually connected to terminal A with respect to a combination of all the other input and output pins connected to terminal B. All pins except the input or output pin being tested and the combination of all the other input and output pins shall be open.



Mil Std 883D
Method 3015.7
Notice 8



PKG. CODE: S8-2		APPROVALS	DATE	MAXIM
CAV./PAD SIZE: 90 X 90	PKG. DESIGN			BUILDSHEET NUMBER: 05-7001-0336 / REV.: B